MC14022B

Octal Counter

The MC14022B is a four−stage Johnson octal counter with built−in code converter. High−speed operation and spike−free outputs are obtained by use of a Johnson octal counter design. The eight decoded outputs are normally low, and go high only at their appropriate octal time period. The output changes occur on the positive−going edge of the clock pulse. This part can be used in frequency division applications as well as octal counter or octal decode display applications.

Features

- Fully Static Operation
- DC Clock Input Circuit Allows Slow Rise Times
- Carry Out Output for Cascading
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low−Power TTL Loads or One Low−Power Schottky TTL Load Over the Rated Temperature Range
- Pin−for−Pin Replacement for CD4022B
- Triple Diode Protection on All Inputs
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q100 Qualified and PPAP Capable
- This Device is Pb−Free and is RoHS Compliant

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Symbol	Parameter	Value	Unit
V_{DD}	DC Supply Voltage Range	−0.5 to +18.0	V
V_{in}, V_{out}	Input or Output Voltage Range (DC or Transient)	−0.5 to V_{DD} + 0.5	V
I_{in}, I_{out}	Input or Output Current (DC or Transient) per Pin	±10	mA
P_D	Power Dissipation, per Package (Note 1)	500	mW
T_A	Ambient Temperature Range	−55 to +125	°C
T_{stg}	Storage Temperature Range	−65 to +150	°C
T_L	Lead Temperature (8−Second Soldering)	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

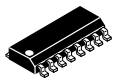
1. Temperature Derating: “D/DW” Packages: –7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high−impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \le (V_{in}$ or $V_{out}) \le V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

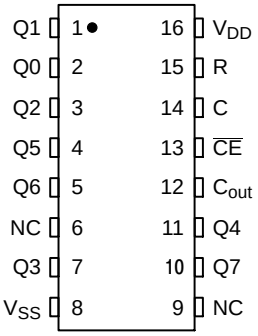
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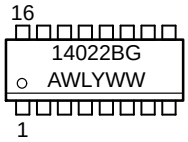
SOIC−16
D SUFFIX
CASE 751B

PIN ASSIGNMENT



NC = NO CONNECTION

MARKING DIAGRAM



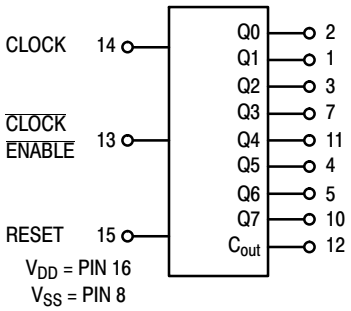
A	= Assembly Location
WL	= Wafer Lot
YY, Y	= Year
WW	= Work Week
G	= Pb−Free Indicator

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

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BLOCK DIAGRAM



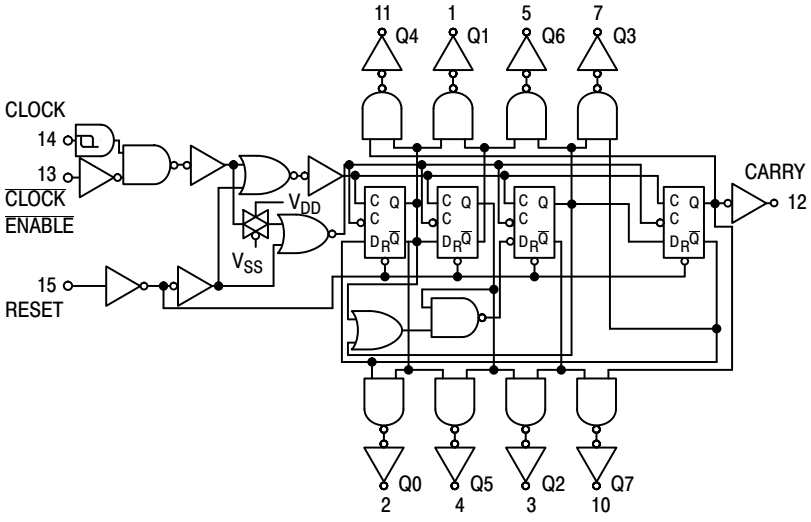
NC = PIN 6, 9

FUNCTIONAL TRUTH TABLE
(Positive Logic)

Clock	$\overline{\text{Clock}}$ $\overline{\text{Enable}}$	Reset	Output=n
0	X	0	n
X	1	0	n
↗	0	0	n+1
↘	X	0	n
1	↘	0	n+1
X	↗	0	n
X	X	1	Q0

X = Don't Care. If n < 4 Carry = 1,
Otherwise = 0.

LOGIC DIAGRAM



ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V_{DD} Vdc	−55°C Min	−55°C Max	25°C Min	25°C Typ (Note 2)	25°C Max	125°C Min	125°C Max	Unit
Output Voltage “0” Level	V_{OL}	5.0	–	0.05	–	0	0.05	–	0.05	Vdc
V_{in} = V_{DD} or 0		10	–	0.05	–	0	0.05	–	0.05	
		15	–	0.05	–	0	0.05	–	0.05	
“1” Level	V_{OH}	5.0	4.95	–	4.95	5.0	–	4.95	–	Vdc
V_{in} = 0 or V_{DD}		10	9.95	–	9.95	10	–	9.95	–	
		15	14.95	–	14.95	15	–	14.95	–	
Input Voltage “0” Level	V_{IL}									Vdc
(V_O = 4.5 or 0.5 Vdc)		5.0	–	1.5	–	2.25	1.5	–	1.5	
(V_O = 9.0 or 1.0 Vdc)		10	–	3.0	–	4.50	3.0	–	3.0	
(V_O = 13.5 or 1.5 Vdc)		15	–	4.0	–	6.75	4.0	–	4.0	
“1” Level	V_{IH}									Vdc
(V_O = 0.5 or 4.5 Vdc)		5.0	3.5	–	3.5	2.75	–	3.5	–	
(V_O = 1.0 or 9.0 Vdc)		10	7.0	–	7.0	5.50	–	7.0	–	
(V_O = 1.5 or 13.5 Vdc)		15	11	–	11	8.25	–	11	–	
Output Drive Current	I_{OH}									mAdc
(V_{OH} = 2.5 Vdc) Source		5.0	–3.0	–	–2.4	–4.2	–	–1.7	–	
(V_{OH} = 4.6 Vdc)		5.0	–0.64	–	–0.51	–0.88	–	–0.36	–	
(V_{OH} = 9.5 Vdc)		10	–1.6	–	–1.3	–2.25	–	–0.9	–	
(V_{OH} = 13.5 Vdc)		15	–4.2	–	–3.4	–8.8	–	–2.4	–	
(V_{OL} = 0.4 Vdc) Sink	I_{OL}	5.0	0.64	–	0.51	0.88	–	0.36	–	mAdc
(V_{OL} = 0.5 Vdc)		10	1.6	–	1.3	2.25	–	0.9	–	
(V_{OL} = 1.5 Vdc)		15	4.2	–	3.4	8.8	–	2.4	–	
Input Current	I_{in}	15	–	±0.1	–	±0.00001	±0.1	–	±1.0	μAdc
Input Capacitance (V_{in} = 0)	C_{in}	–	–	–	–	5.0	7.5	–	–	pF
Quiescent Current (Per Package)	I_{DD}	5.0	–	5.0	–	0.005	5.0	–	150	μAdc
		10	–	10	–	0.010	10	–	300	
		15	–	20	–	0.015	20	–	600	
Total Supply Current (Notes 3 & 4) (Dynamic plus Quiescent, Per Package) (C_L = 50 pF on all outputs, all buffers switching)	I_T	5.0	I_T = (0.28 μA/kHz)f + I_{DD}							μAdc
		10	I_T = (0.56 μA/kHz)f + I_{DD}							
		15	I_T = (0.85 μA/kHz)f + I_{DD}							

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.
3. The formulas given are for the typical characteristics only at 25°C.
4. To calculate total supply current at loads other than 50 pF:

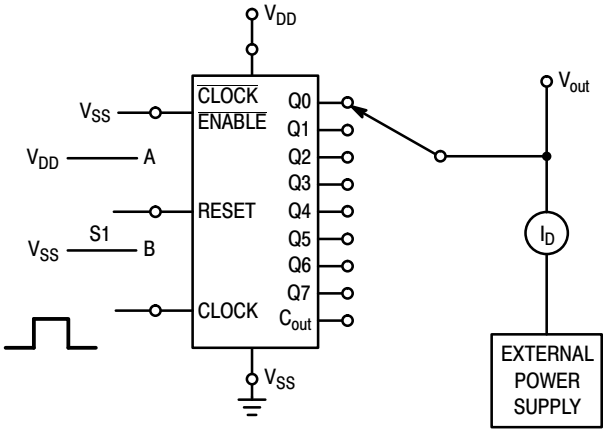
$$I_T(C_L) = I_T(50\ pF) + (C_L - 50)\ Vfk$$

where: I_T is in μA (per package), C_L in pF, V = (V_{DD} – V_{SS}) in volts, f in kHz is input frequency, and k = 0.00125.

SWITCHING CHARACTERISTICS (Note 5) (C_L = 50 pF, T_A = 25°C)

Characteristic	Symbol	V_{DD} Vdc	Min	Typ (Note 6)	Max	Unit
Output Rise and Fall Time	t_{TLH},					ns
t_{TLH}, t_{THL} = (1.5 ns/pF) C_L + 25 ns	t_{THL}	5.0	−	100	200	
t_{TLH}, t_{THL} = (0.75 ns/pF) C_L + 12.5 ns		10	−	50	100	
t_{TLH}, t_{THL} = (0.55 ns/pF) C_L + 9.5 ns		15	−	40	80	
Propagation Delay Time	t_{PLH},					ns
Reset to Decode Output	t_{PHL}					
t_{PLH}, t_{PHL} = (1.7 ns/pF) C_L + 415 ns		5.0	−	500	1000	
t_{PLH}, t_{PHL} = (0.66 ns/pF) C_L + 197 ns		10	−	230	460	
t_{PLH}, t_{PHL} = (0.5 ns/pF) C_L + 150 ns		15	−	175	350	
Propagation Delay Time	t_{PLH},					ns
Clock to C_{out}	t_{PHL}					
t_{PLH}, t_{PHL} = (1.7 ns/pF) C_L + 315 ns		5.0	−	400	800	
t_{PLH}, t_{PHL} = (0.66 ns/pF) C_L + 142 ns		10	−	175	350	
t_{PLH}, t_{PHL} = (0.5 ns/pF) C_L + 100 ns		15	−	125	250	
Propagation Delay Time	t_{PLH},					ns
Clock to Decode Output	t_{PHL}					
t_{PLH}, t_{PHL} = (1.7 ns/pF) C_L + 415 ns		5.0	−	275	1000	
t_{PLH}, t_{PHL} = (0.66 ns/pF) C_L + 197 ns		10	−	125	460	
t_{PLH}, t_{PHL} = (0.5 ns/pF) C_L + 150 ns		15	−	95	350	
Turn−Off Delay Time	t_{PLH}					ns
Reset to C_{out}						
t_{PLH} = (1.7 ns/pF) C_L + 315 ns		5.0	−	400	800	
t_{PLH} = (0.66 ns/pF) C_L + 142 ns		10	−	175	350	
t_{PLH} = (0.5 ns/pF) C_L + 100 ns		15	−	125	250	
Clock Pulse Width	t_{WH}	5.0	250	125	−	ns
		10	100	50	−	
		15	75	35	−	
Clock Frequency	f_{cl}	5.0	−	5.0	2.0	MHz
		10	−	12	5.0	
		15	−	16	6.7	
Reset Pulse Width	t_{WH}	5.0	500	250	−	ns
		10	250	125	−	
		15	190	95	−	
Reset Removal Time	t_{rem}	5.0	750	375	−	ns
		10	275	135	−	
		15	210	105	−	
Clock Input Rise and Fall Time	t_{TLH}, t_{THL}	5.0	No Limit			−
		10				
		15				
$\overline{\text{Clock Enable}}$ Setup Time	t_{su}	5.0	350	175	−	ns
		10	150	75	−	
		15	115	52	−	
$\overline{\text{Clock Enable}}$ Removal Time	t_{rem}	5.0	420	260	−	ns
		10	200	100	−	
		15	140	70	−	

5. The formulas given are for the typical characteristics only at 25°C.
6. Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.



Outputs	Output Sink Drive (S1 to A)	Output Source Drive Clock to desired Output (S1 to B)
Carry	Clock to Q5 thru Q7 (S1 to B)	S1 to A
V_{GS} =	V_{DD}	$-V_{DD}$
V_{DS} =	V_{out}	$V_{out} - V_{DD}$

Figure 1. Typical Output Source and Output Sink Characteristics Test Circuit

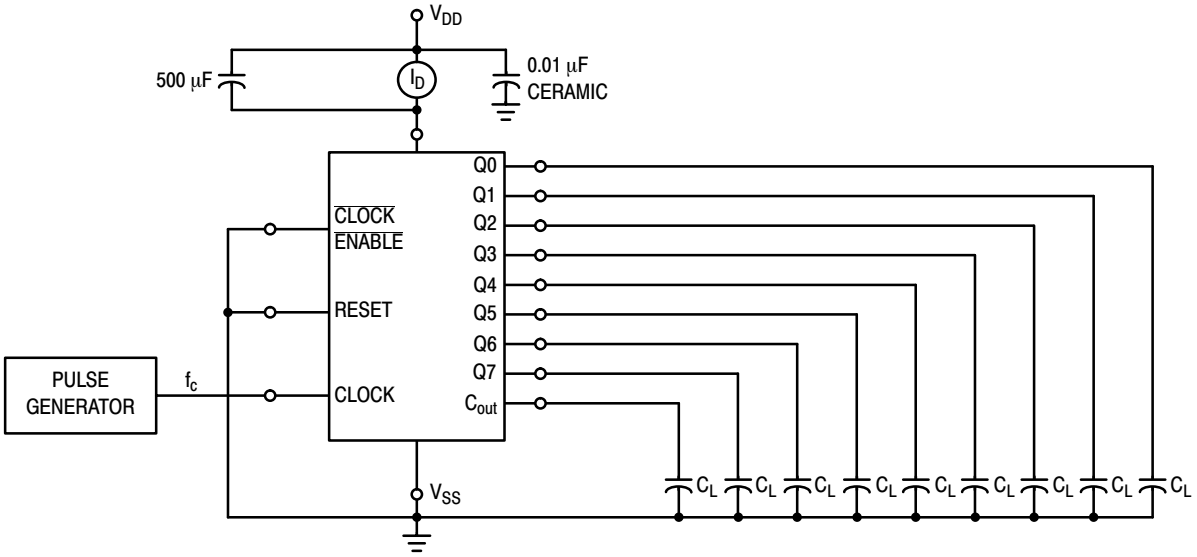


Figure 2. Typical Power Dissipation Test Circuit

APPLICATIONS INFORMATION

Figure 3 shows a technique for extending the number of decoded output states for the MC14022B. Decoded outputs are sequential within each stage and from stage to stage, with no dead time (except propagation delay).

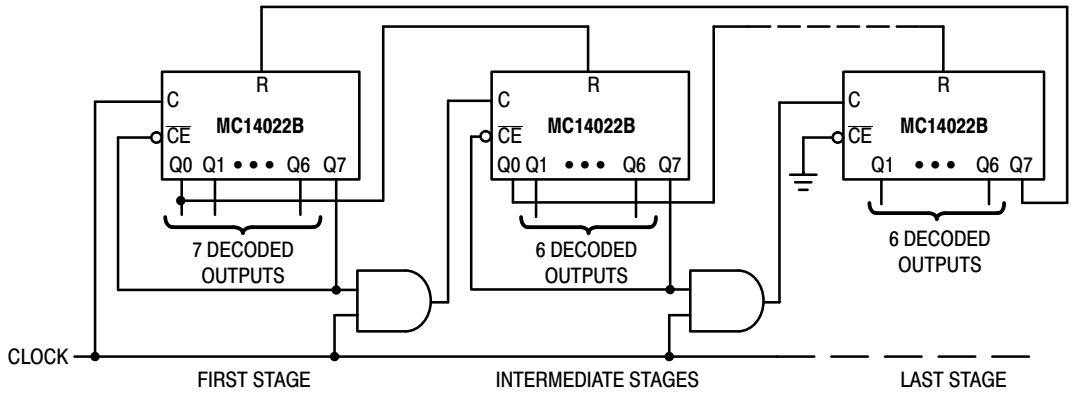


Figure 3. Counter Expansion

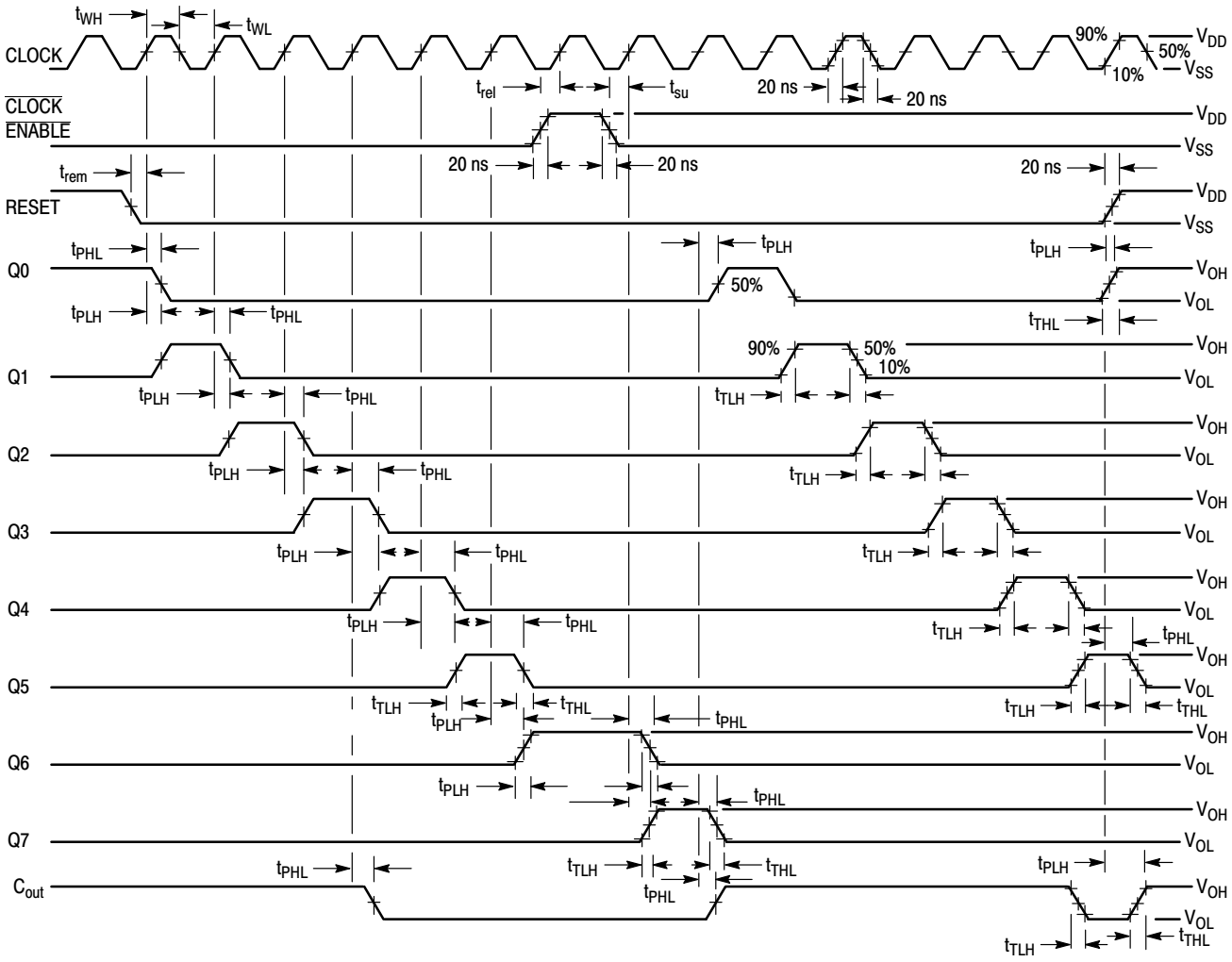


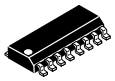
Figure 4. AC Measurement Definition and Functional Waveforms

ORDERING INFORMATION

Device	Package	Shipping†
MC14022BDG	SOIC−16 (Pb−Free)	48 Units / Rail
MC14022BDR2G	SOIC−16 (Pb−Free)	2500 Units / Tape & Reel
NLV14022BDR2G*	SOIC−16 (Pb−Free)	2500 Units / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

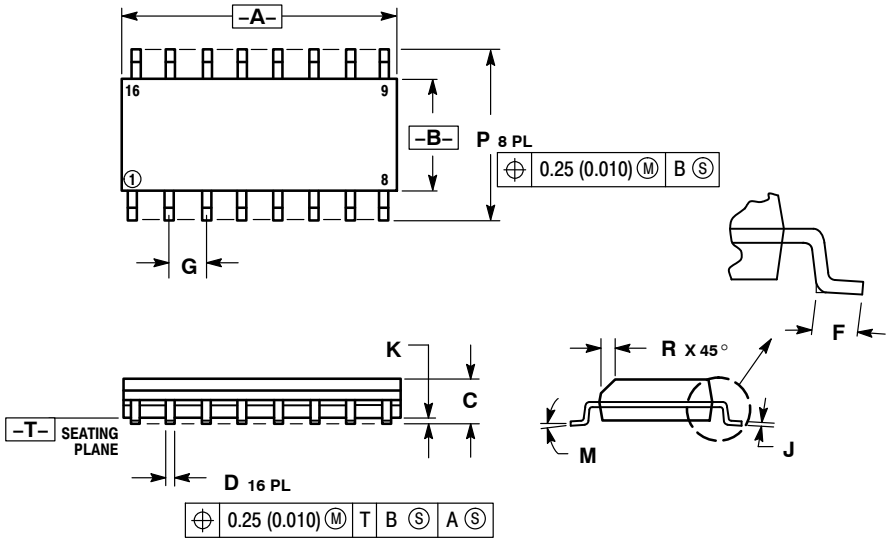
*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q100 Qualified and PPAP Capable.



SCALE 1:1

SOIC–16
CASE 751B–05
ISSUE K

DATE 29 DEC 2006



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

STYLE 1:
PIN 1. COLLECTOR
2. BASE
3. EMITTER
4. NO CONNECTION
5. EMITTER
6. BASE
7. COLLECTOR
8. COLLECTOR
9. BASE
10. EMITTER
11. NO CONNECTION
12. EMITTER
13. BASE
14. COLLECTOR
15. EMITTER
16. COLLECTOR

STYLE 2:
PIN 1. CATHODE
2. ANODE
3. NO CONNECTION
4. CATHODE
5. CATHODE
6. NO CONNECTION
7. ANODE
8. CATHODE
9. CATHODE
10. ANODE
11. NO CONNECTION
12. CATHODE
13. CATHODE
14. NO CONNECTION
15. ANODE
16. CATHODE

STYLE 3:
PIN 1. COLLECTOR, DYE #1
2. BASE, #1
3. EMITTER, #1
4. COLLECTOR, #1
5. COLLECTOR, #2
6. BASE, #2
7. EMITTER, #2
8. COLLECTOR, #2
9. COLLECTOR, #3
10. BASE, #3
11. EMITTER, #3
12. COLLECTOR, #3
13. COLLECTOR, #4
14. BASE, #4
15. EMITTER, #4
16. COLLECTOR, #4

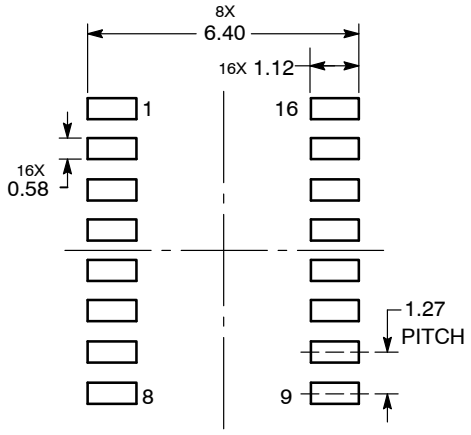
STYLE 4:
PIN 1. COLLECTOR, DYE #1
2. COLLECTOR, #1
3. COLLECTOR, #2
4. COLLECTOR, #2
5. COLLECTOR, #3
6. COLLECTOR, #3
7. COLLECTOR, #4
8. COLLECTOR, #4
9. BASE, #4
10. EMITTER, #4
11. BASE, #3
12. EMITTER, #3
13. BASE, #2
14. EMITTER, #2
15. BASE, #1
16. EMITTER, #1

STYLE 5:
PIN 1. DRAIN, DYE #1
2. DRAIN, #1
3. DRAIN, #2
4. DRAIN, #2
5. DRAIN, #3
6. DRAIN, #3
7. DRAIN, #4
8. DRAIN, #4
9. GATE, #4
10. SOURCE, #4
11. GATE, #3
12. SOURCE, #3
13. GATE, #2
14. SOURCE, #2
15. GATE, #1
16. SOURCE, #1

STYLE 6:
PIN 1. CATHODE
2. CATHODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE
7. CATHODE
8. CATHODE
9. ANODE
10. ANODE
11. ANODE
12. ANODE
13. ANODE
14. ANODE
15. ANODE
16. ANODE

STYLE 7:
PIN 1. SOURCE N-CH
2. COMMON DRAIN (OUTPUT)
3. COMMON DRAIN (OUTPUT)
4. GATE P-CH
5. COMMON DRAIN (OUTPUT)
6. COMMON DRAIN (OUTPUT)
7. COMMON DRAIN (OUTPUT)
8. SOURCE P-CH
9. SOURCE P-CH
10. COMMON DRAIN (OUTPUT)
11. COMMON DRAIN (OUTPUT)
12. COMMON DRAIN (OUTPUT)
13. GATE N-CH
14. COMMON DRAIN (OUTPUT)
15. COMMON DRAIN (OUTPUT)
16. SOURCE N-CH

SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

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